



DGD2190

HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO-8

Description

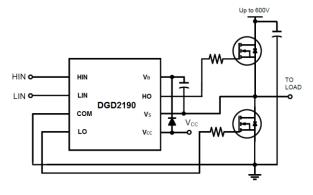
The DGD2190 is a high voltage/high speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD2190's high-side to switch to 600V in a bootstrap operation under high dV/dt conditions.

The DGD2190 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction.

The DGD2190 is offered in the SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



Typical Configuration

Features

- Floating High-Side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in a Half-Bridge Configuation
- Output Drivers Capable of 4.5A/4.5A Typ Sink/Source
- Logic Input (HIN and LIN) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull-Down
- Undervoltage Lockout for High and Low-Side Drivers
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208
- Weight: 0.075 grams (Approximate)



SO-8 (Type TH) Top View

Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DGD2190S8-13	DGD2190	13	12	2,500

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

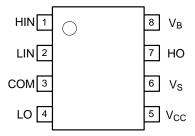
Marking Information



⊃∷ = Manufacturer's marking DGD2190 = Product Type Marking Code YY = Year (ex: 17 = 2017) WW = Week (01 to 53)



Pin Diagrams

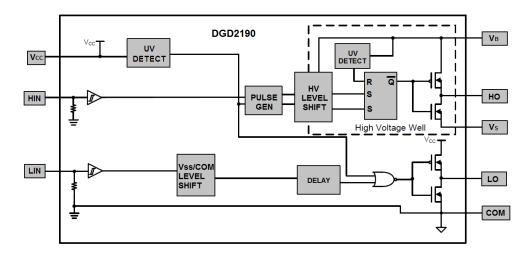


Top View: SO-8 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	HIN	Logic Input for High-side Gate Driver Output, in Phase with HO
2	LIN	Logic Input for Low-side Gate Driver Output, in Phase with LO
3	COM	Low-Side and Logic Return
4	LO	Low-Side Gate Drive Output
5	V _{CC}	Low-Side and Logic Fixed Supply
6	Vs	High-Side Floating Supply Return
7	НО	High-Side Gate Drive Output
8	V _B	High-Side Floating Supply

Functional Block Diagram





DGD2190

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side Floating Supply Voltage	V _B	-0.3 to +624	V
High-side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
High-side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Low-side and Logic Fixed Supply Voltage	Vcc	-0.3 to +24	V
Low-side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (HIN and LIN)	Vin	-0.3 to V _{CC} +0.3	V

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P _D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Case (Note 5)	R ₀ JC	45	°C/W
Operating Temperature	TJ	+150	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-side Floating Supply Absolute Voltage	V_{B}	V _S +10	V _S +20	V
High-side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High-side Floating Output Voltage	V_{HO}	Vs	V_{B}	V
Low-side Fixed Supply Voltage	Vcc	10	20	V
Low-side Output Voltage	V_{LO}	0	V _{CC}	V
Logic Input Voltage (HIN and LIN)	V_{IN}	0	5	V
Ambient Temperature	T _A	-40	+125	°C

Notes:

^{5.} When mounted on a standard JEDEC 2-layer FR-4 board.

^{6.} Logic operation for Vs of -5V to +600V. Logic state held for Vs of -5V to -VBs.



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$\textbf{DC Electrical Characteristics} \ (V_{BIAS} \ (V_{CC}, V_{BS}) = 15V, \ @T_A = +25^{\circ}C, \ unless \ otherwise \ specified.) \ (Note \ 7)$

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Logic "1" Input Voltage	V _{IH}	2.5	_	_	V	V _{CC} = 10V to 20V
Logic "0" Input Voltage	V_{IL}	_	_	0.8	V	V _{CC} = 10V to 20V
High Level Output Voltage, VBIAS - VO	VoH	_	_	0.1	V	$I_O = 0mA$
Low Level Output Voltage, VO	V_{OL}	_	_	0.035	V	$I_O = 0mA$
Offset Supply Leakage Current	I _{LK}	_	_	50	μΑ	$V_B = V_S = 600V$
Quiescent V _{BS} Supply Current	I _{BSQ}	_	45	80	μΑ	V _{IN} = 0V or 5V
Quiescent V _{CC} Supply Current	Iccq	_	75	200	μΑ	V _{IN} = 0V or 5V
Logic "1" Input Bias Current	I _{IN+}	_	25	50	μΑ	$V_{IN} = 5V$
Logic "0" Input Bias Current	I _{IN-}	_	1.0	2.0	μΑ	$V_{IN} = 0V$
V _{BS} Supply Undervoltage Positive Going Threshold	V_{BSUV+}	7.6	8.4	9.8	V	_
V _{BS} Supply Undervoltage Negative Going Threshold	V _{BSUV} -	6.9	7.8	9.0	V	_
V _{CC} Supply Undervoltage Positive Going Threshold	V _{CCUV+}	7.6	8.4	9.8	V	_
V _{CC} Supply Undervoltage Negative Going Threshold	V _{CCUV} -	6.9	7.8	9.0	V	_
V and V Undervolte as Unstarceia	V _{CCUVH}	_	0.6	_	V	_
V _{CC} and V _{BS} Undervoltage Hysteresis	V _{BSUVH}	_	0.6	_	V	_
Output High Short Circuit Pulsed Current	I _{O+}	3.5	4.5	_	Α	$V_O = 0V$, PW ≤ 10 ms
Output Low Short Circuit Pulsed Current	I _O -	3.5	4.5	_	Α	V _O = 15V, PW ≤ 10ms

Note: 7. The V_{IN} and I_{IN} parameters are applicable to the two logic pins; HIN and LIN. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Turn-On Propagation Delay	ton	_	140	200	ns	Vs = 0V
Turn-Off Propagation Delay	t _{OFF}	_	140	200	ns	$V_S = 0V$
Delay Matching, HO & LO Turn On/Off	t _{DM}	_	_	50	ns	_
Turn-On Rise Time	t _R	_	25	50	ns	V _S = 0V
Turn-Off Fall Time	t _F	_	20	45	ns	V _S = 0V



Timing Waveforms

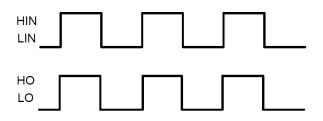


Figure 1. Input / Output Timing Diagram

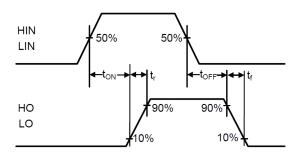


Figure 2. Switching Time Waveform Definitions

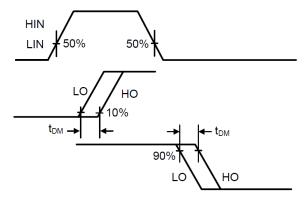


Figure 3. Delay Matching Waveform Definitions



Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

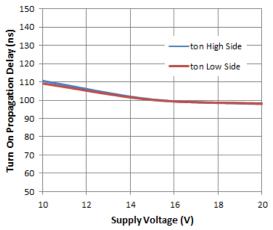


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

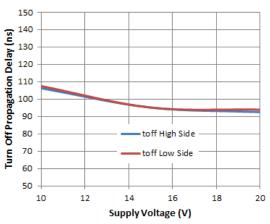


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

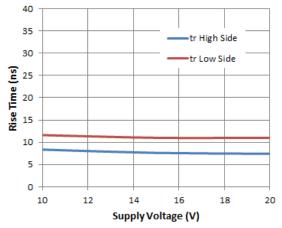


Figure 8. Rise Time vs. Supply Voltage

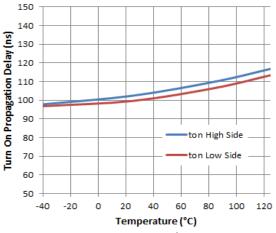


Figure 5. Turn-on Propagation Delay vs. Temperature

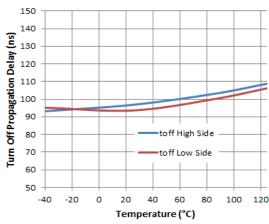


Figure 7. Turn-off Propagation Delay vs. Temperature

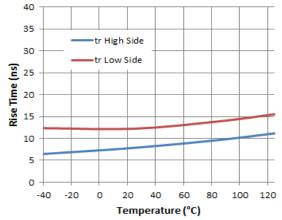


Figure 9. Rise Time vs. Temperature



Typical Performance Characteristics (Cont.) (@T_A = +25°C, unless otherwise specified.)

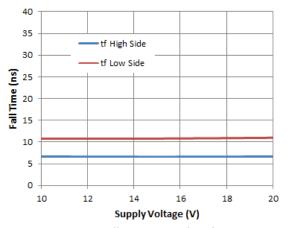


Figure 10. Fall Time vs. Supply Voltage

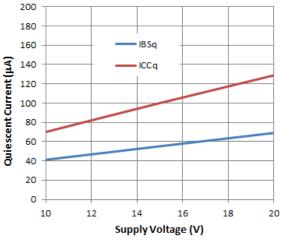


Figure 12. Quiescent Current vs. Supply Voltage

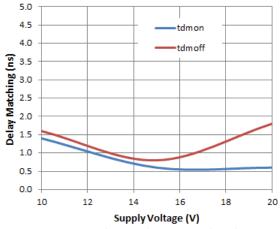


Figure 14. Delay Matching vs. Supply Voltage

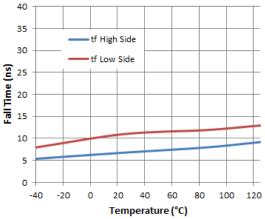


Figure 11. Fall Time vs. Temperature

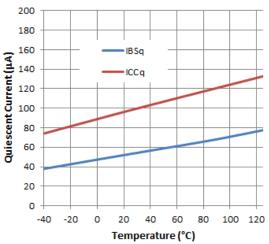


Figure 13. Quiescent Current vs. Temperature

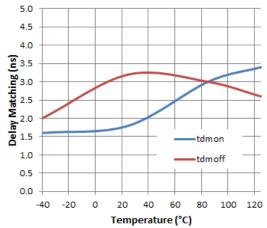


Figure 15. Delay Matching vs. Temperature

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Typical Performance Characteristics (Cont.) (@T_A = +25°C, unless otherwise specified.)

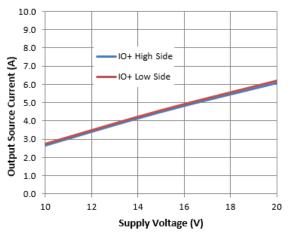


Figure 16. Output Source Current vs. Supply Voltage

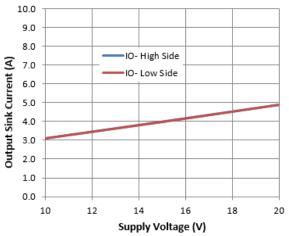


Figure 18. Output Sink Current vs. Supply Voltage

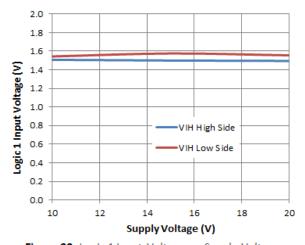


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

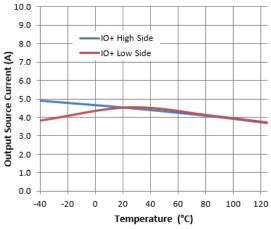


Figure 17. Output Source Current vs. Temperature

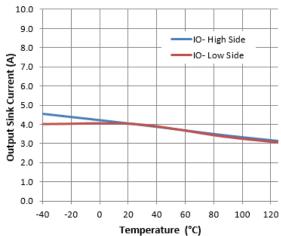


Figure 19. Output Sink Current vs. Temperature

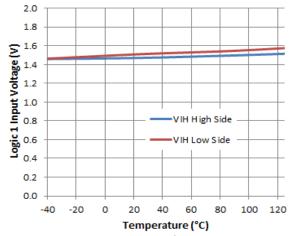


Figure 21. Logic 1 Input Voltage vs. Temperature



Typical Performance Characteristics (Cont.) (@T_A = +25°C, unless otherwise specified.)

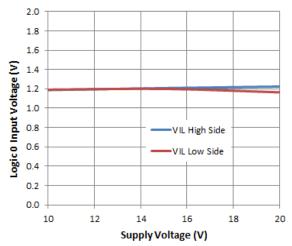


Figure 22. Logic O Input Voltage vs. Supply Voltage

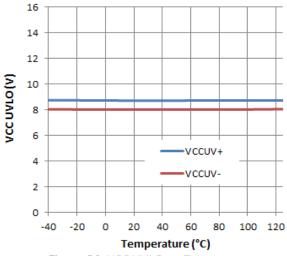


Figure 24. VCC UVLO vs. Temperature

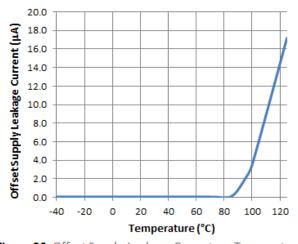


Figure 26. Offset Supply Leakage Current vs. Temperature

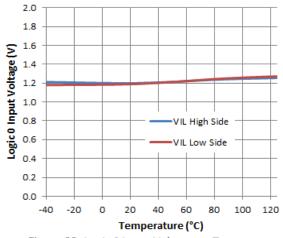


Figure 23. Logic 0 Input Voltage vs. Temperature

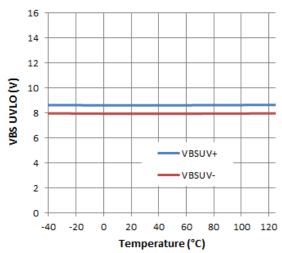


Figure 25. VBS UVLO vs. Temperature

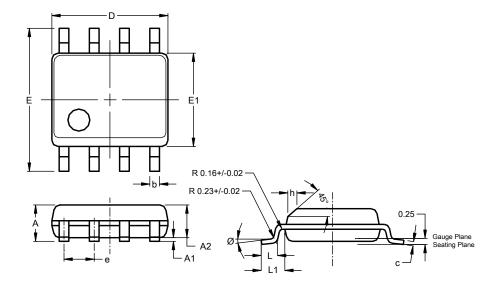


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)

USE DGD2190M

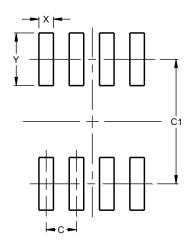


SO-8 (Type TH)					
Dim	Min	Max	Тур		
Α	1.35	1.75	-		
A1	0.10	0.25	_		
A2	1	1	1.45		
b	0.35	0.51	_		
С	0.190	0.248	_		
D	4.80	5.00	4.90		
Е	5.80	6.20	6.00		
E1	3.80	4.00	3.90		
е	_	_	1.27		
h	0.25	0.50	_		
L	0.41	1.27	_		
L1	_	_	1.04		
Ø	0°	8°	_		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)
С	1.27
C1	5.20
Х	0.60
Υ	2.20

For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking. Note:



DGD2190

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